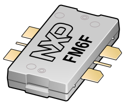


SOT1740-1

FM6F, flange mount flat package; 6 terminals; 3.05 mm pitch, 9.02 mm x 17.53 mm x 2.59 mm body

14 August 2020 Package information

1 Package summary

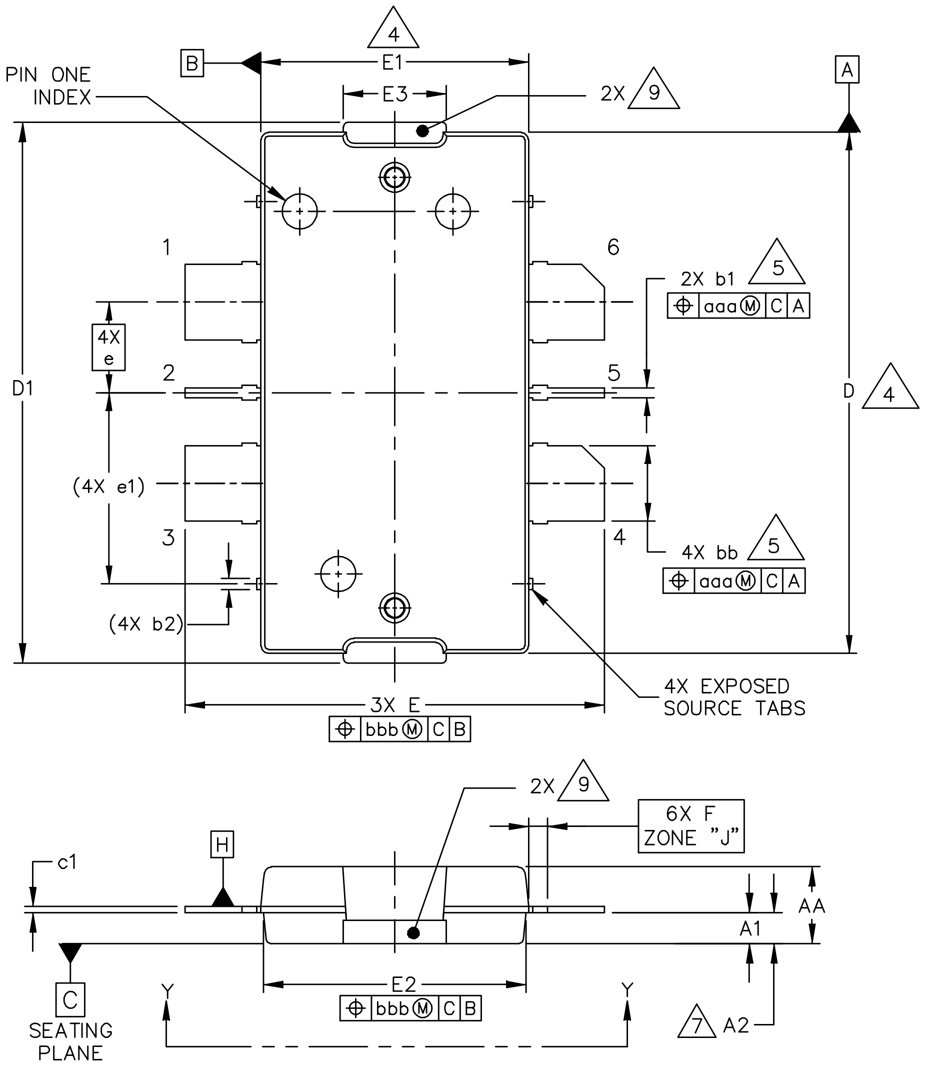
Terminal position code	D (double)
Package type descriptive code	FM6F
Package type industry code	FM6F
Package style descriptive code	DFM (double-ended flange mount)
Mounting method type	F (flange mount)
Issue date	12-06-2020
Manufacturer package code	98ASA00592D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	17.48	17.53	17.58	mm
package width	8.97	9.02	9.07	mm
seated height	2.51	2.59	2.67	mm
nominal pitch	-	3.05	-	mm
actual quantity of termination	-	6	-	

2 Package outline

TO–270WB–6A SOT1740–1



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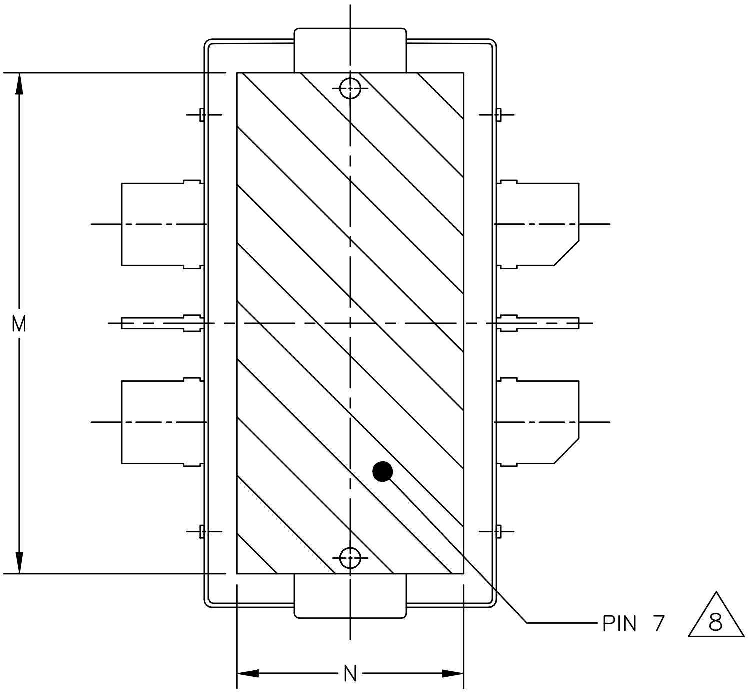
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA00592D	REVISION: B	

Figure 1. Package outline FM6F (SOT1740-1)

TO–270WB–6A

SOT1740–1



VIEW Y–Y

DATE: 12 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA00592D	REVISION: B	

Figure 2. Package outline detail FM6F (SOT1740-1)

TO–270WB–6A SOT1740–1

NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M–1994.

3. DATUM PLANE H IS LOCATED AT THE TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.

4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE. DIMENSIONS D AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

5. DIMENSIONS bb AND b1 DO NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE bb AND b1 DIMENSIONS AT MAXIMUM MATERIAL CONDITION.

6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

7. DIMENSION A2 APPLIES WITHIN ZONE J ONLY.

8. HATCHING REPRESENTS THE EXPOSED AND SOLDERABLE AREA OF THE HEAT SLUG. DIMENSIONS M AND N REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF THE HEAT SLUG.

9. THESE SURFACES OF THE HEAT SLUG ARE NOT PART OF THE SOLDERABLE SURFACES AND MAY REMAIN UNPLATED.

	INCH		MILLIMETER			INCH		MILLIMETER	
DIM	MIN	MAX	MIN	MAX	DIM	MIN	MAX	MIN	MAX
AA	.099	.105	2.51	2.67	M	.600	---	15.24	---
A1	.037	.045	0.94	1.14	N	.270	---	6.86	---
A2	.040	.042	1.02	1.07	bb	.097	.103	2.46	2.62
D	.688	.692	17.48	17.58	b1	.010	.016	0.25	0.41
D1	.712	.720	18.08	18.29	b2	---	.019	---	0.48
E	.551	.559	14.00	14.20	c1	.007	.011	0.18	0.28
E1	.353	.357	8.97	9.07	e	.120 BSC		3.05 BSC	
E2	.346	.350	8.79	8.89	e1	.253 INFO ONLY		6.43 INFO ONLY	
E3	.132	.140	3.35	3.56	aaa	.004		0.10	
F	.025 BSC		0.64 BSC		bbb	.008		0.20	

DATE: 12 JUN 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA00592D	REVISION: B	

Figure 3. Package outline note FM6F (SOT1740-1)

3 Legal information

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